



IFW

Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID: 53331

Application ID: 10667759



Title of Invention:

METHODS OF MAKING THIN
INTEGRATED CIRCUIT DEVICE
PACKAGES WITH IMPROVED
THERMAL PERFORMANCE

First Named Inventor: Sean Crowley

Domestic/Foreign Application: Domestic Application

Filing Date: 2003-09-22

Effective Receipt Date: 2004-01-08

Submission Type: Information Disclosure
Statement

Filing Type:

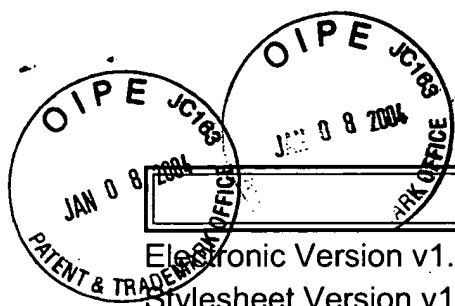
Confirmation number: 1384

Attorney Docket Number: AMKOR022CB

Total Fees Authorized:


Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark
Office,ou=Department of Commerce,o=U.S. Government,c=US

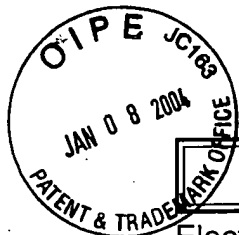
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TRANSMITTAL

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	METHODS OF MAKING THIN INTEGRATED CIRCUIT DEVICE PACKAGES WITH IMPROVED THERMAL PERFORMANCE									
<p>Application Number: 10/667759 </p> <p>Date: 2003-09-22</p> <p>First Named Applicant: Sean T. Crowley</p> <p>Confirmation Number: 1384</p> <p>Attorney Docket Number: AMKOR022CB</p>										
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>										
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

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METHODS OF MAKING THIN INTEGRATED CIRCUIT
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PERFORMANCE

Application Number: 10/667759



Confirmation Number: 1384

First Named Applicant: Sean Crowley

Attorney Docket Number: AMKOR022CB

Art Unit: 2811

Search string: (6395578 or 6400004 or 6410979 or 6414385
or 6420779 or 6429508 or 6437429 or 6444499
or 6448633 or 6452279 or 6464121 or 6476469
or 6476474 or 6482680 or 6498099 or 6498392
or 6507096 or 6507120 or 6534849 or 6559525
or 6566168).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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	2	6400004	2002-06-04	FAN ET AL.			
	3	6410979	2002-06-25	ABE			
	4	6414385	2002-07-02	HUANG ET AL.			
	5	6420779	2002-07-16	SHARMA ET AL.			
	6	6429508	2002-08-06	GANG			
	7	6437429	2002-08-20	SU ET AL.			
	8	6444499	2002-09-03	SWISS ET AL.			
	9	6448633	2002-09-10	YEE ET AL.			
	10	6452279	2002-09-17	SHIMODA			
	11	6464121	2002-10-15	REIJNDERS			
	12	6476469	2002-11-05	HUNG ET AL.			
	13	6476474	2002-11-05	HUNG			
	14	6482680	2002-11-19	KHOR ET AL.			

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	16	6498392	2002-12-24	AZUMA
	17	6507096	2003-01-14	GANG
	18	6507120	2003-01-14	LO ET AL.
	19	6534849	2003-03-18	GANG
	20	6559525	2003-05-06	HUANG
	21	6566168	2003-05-20	GANG

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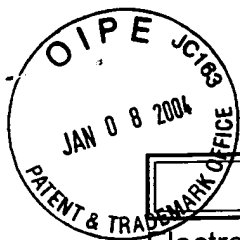
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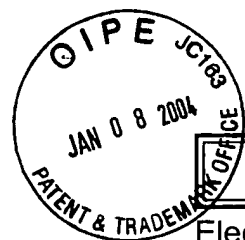
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Attorney Docket Number: AMKOR022CB
Art Unit: 2811



Search string: (6197615 or 6198171 or 6201186 or 6201292
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or 6369447 or 6369454 or 6373127 or 6380048
or 6384472 or 6388336).pn.

US Patent Documents

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init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6197615	2001-03-06	SONG ET AL			
	2	6198171	2001-03-06	HUANG ET AL			
	3	6201186	2001-03-13	DANIELS ET AL			
	4	6201292	2001-03-13	YAGI ET AL			
	5	6204554	2001-03-20	EWER ET AL			
	6	6208020	2001-03-27	MINAMIO			
	7	6208021	2001-03-27	OHUCHI ET AL			
	8	6208023	2001-03-27	NAKAYAMA ET AL			

	9	6211462	2001-04-03	CARTER, JR. ET AL
	10	6218731	2001-04-17	HUANG ET AL.
	11	6222258	2001-04-24	ASANO ET AL
	12	6225146	2001-05-01	YAMAGUCHI ET AL
	13	6229200	2001-05-08	MCLELLAN ET AL
	14	6229205	2001-05-08	JEONG ET AL
	15	6239367	2001-05-29	HSUAN ET AL.
	16	6239384	2001-05-29	SMITH ET AL
	17	6242281	2001-06-05	MCLELLAN ET AL
	18	6256200	2001-07-03	LAM ET AL
	19	6258629	2001-07-10	NIONES ET AL
	20	6281566	2001-08-28	MAGNI
	21	6281568	2001-08-28	GLENN ET AL.
	22	6282095	2001-08-28	HOUGHTON ET AL.
	23	6285075	2001-09-04	COMBS ET AL.
	24	6291271	2001-09-18	LEE ET AL.
	25	6291273	2001-09-18	MIYAKI ET AL.
	26	6294100	2001-09-25	FAN ET AL.
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	29	6297548	2001-10-02	MODEN ET AL.
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	34	6316822	2001-11-13	VENKATESHWARAN ET AL.
	35	6316838	2001-11-13	OZAWA ET AL.
	36	6323550	2001-11-27	MARTIN ET AL.
	37	6326243	2001-12-04	SUZUYA ET AL.
	38	6326244	2001-12-04	BROOKS ET AL.
	39	6326678	2001-12-04	KARMEZOS ET AL.
	40	6335564	2002-01-01	POUR
	41	6337510	2002-01-08	CHUN-JEN ET AL.
	42	6339255	2002-01-15	SHIN
	43	6348726	2002-02-19	BAYAN ET AL.
	44	6355502	2002-03-12	KANG ET AL.

	45	6369447	2002-04-09	MORI
	46	6369454	2002-04-09	CHUNG
	47	6373127	2002-04-16	BAUDOUIN ET AL.
	48	6380048	2002-04-30	BOON ET AL.
	49	6384472	2002-05-07	HUANG
	50	6388336	2002-05-14	VENKATESHWARAN ET AL.

Signature

Examiner Name	Date



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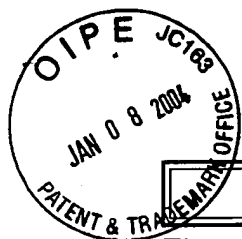
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Confirmation number: 1384

Attorney Docket Number: AMKOR022CB


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Search string: (5909053 or 5915998 or 5917242 or 5939779
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or 6169329 or 6177718 or 6181002 or 6184465
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US Patent Documents

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	50	6194777	2001-02-27	ABBOTT ET AL

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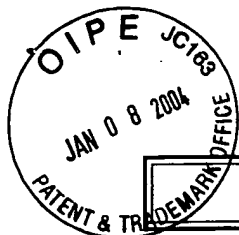


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	6	5650663	1997-07-22	PARTHASARANTHI			
	7	5661088	1997-08-26	TESSIER ET AL.			
	8	5665996	1997-09-09	WILLIAMS ET AL.			

9	5673479	1997-10-07	HAWTHORNE
10	5683806	1997-11-04	SAKUMOTO ET AL.
11	5689135	1997-11-18	BALL
12	5696666	1997-12-09	MILES ET AL.
13	5701034	1997-12-23	MARRS
14	5703407	1997-12-30	HORI
15	5710064	1998-01-20	SONG ET AL.
16	5723899	1998-03-03	SHIN
17	5724233	1998-03-03	HONDA ET AL.
18	5736432	1998-04-07	MACKESSY
19	5745984	1998-05-05	COLE, JR. ET AL.
20	5753532	1998-05-19	SIM
21	5753977	1998-05-19	KUSAKA ET AL.
22	5766972	1998-06-16	TAKAHASHI ET AL.
23	5770888	1998-06-23	SONG ET AL.
24	5776798	1998-07-07	QUAN ET AL.
25	5783861	1998-07-21	SON
26	5801440	1998-09-01	CHU ET AL.
27	5814877	1998-09-29	DIFFENDERFER ET AL.
28	5814881	1998-09-29	ALAGARATNAM ET AL.
29	5814883	1998-09-29	SAWAI ET AL.
30	5814884	1998-09-29	DAVIS ET AL.
31	5817540	1998-10-06	WARK
32	5818105	1998-10-06	KOUDA
33	5821457	1998-10-13	MOSLEY ET AL.
34	5821615	1998-10-13	LEE
35	5834830	1998-11-10	CHO
36	5835988	1998-11-10	ISHII
37	5844306	1998-12-01	FUJITA ET AL.
38	5856911	1999-01-05	RILEY
39	5859471	1999-01-12	KURAISHI ET AL.
40	5866939	1999-02-02	SHIN ET AL.
41	5871782	1999-02-16	CHOI
42	5874784	1999-02-23	AOKI ET AL.
43	5877043	1999-03-02	ALCOE ET AL.
44	5886397	1999-03-23	EWER

	45	5886398	1999-03-23	LOW ET AL.
	46	5894108	1999-04-13	MOSTAFAZADEH ET AL.
	47	5897339	1999-04-27	SONG ET AL.
	48	5900676	1999-05-04	KWEON ET AL.
	49	5903049	1999-05-11	MORI
	50	5903050	1999-05-11	THURAIRAJARATNAM ET AL.

Signature

Examiner Name	Date